

Ecner Array

Product Overview

The Ecner Array Packing Element System is designed to withstand high temperature and high-pressure applications. It has OEM's Anti-Extrusion Backup System that allows it to perform in elevated applications.

Features

- Field Tested
 - Up to 15kpsi
 - Up to 450°F
- Permanent and Retrievable Applications
- NBR, HNBR, AFLAS and FKM Material Options
- Low Setting Load
- Anti-Extrusion Backup System
- H2S and CO2 Resistant Options
- Industry used for decades

Applications

- Completions
- Well Intervention
- Wellbore Cleanup
- Production

